

N-Channel 60-V (D-S) MOSFET

PRODUC	T SUMMARY		
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (A) ^a	Q _g (Typ.)
60	0.075 at V _{GS} = 10 V	4.0	21.00
	$0.086 \text{ at V}_{GS} = 4.5 \text{ V}$	3.8	2.1 nC

FEATURES

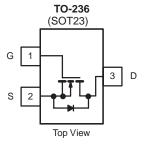
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

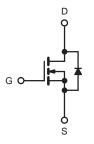
RoHS HALOGEN

FREE

APPLICATIONS

- Battery Switch
- DC/DC Converter





N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 2$	25 °C, unless oth	erwise noted		
Parameter		Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	60	V	
Gate-Source Voltage		V_{GS}	± 20	V
	T _C = 25 °C		4.0	
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	ı_	3.4	
Continuous Diain Current (1) = 130 C)	T _A = 25 °C	I _D	3.1 ^{b, c}	
	T _A = 70 °C		2.5 ^{b, c}	A
Pulsed Drain Current		I _{DM}	12	^
Continuous Source-Drain Diode Current	T _C = 25 °C	I-	1.39	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.91 ^{b, c}	
Avalanche Current	L = 0.1 mH	I _{AS}	6	
Single-Pulse Avalanche Energy	L=0.11111	E _{AS}	1.8	mJ
	T _C = 25 °C		1.66	
Maximum Dawar Dissination	T _C = 70 °C	ь	1.06	W
Maximum Power Dissipation	T _A = 25 °C	P _D	1.09 ^{b, c}	VV
	T _A = 70 °C		0.7 ^{b, c}	
Operating Junction and Storage Temperature Range	perating Junction and Storage Temperature Range		- 55 to 150	°C

THERMAL RESISTANCE RATINGS								
Parameter		Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	90	115	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	C/VV			

- a. Based on T_C = 25 °C.
 b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 120 °C/W.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					L		
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			55		m\//0C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	I _D = 250 μA		- 5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Oata Wallana Basin Oamani		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	^	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 55 °C			10	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	8			Α	
	В	$V_{GS} = 10 \text{ V}, I_D = 1.9 \text{ A}$		0.075			
Orain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 1.7 \text{ A}$		0.086		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15V, I _D = 1.9 A		5		S	
Dynamic ^b				1	I.		
Input Capacitance	C _{iss}			180			
Output Capacitance	C _{oss}			22			
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		13		pF	
Total Oats Observe		V _{DS} = 30 V, V _{GS} = 10 V, I _D = 1.9 A		4.2	6.1		
Total Gate Charge	Qg			2.1	3.2		
Gate-Source Charge	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 1.9 \text{ A}$		0.7		nC	
Gate-Drain Charge	Q_{gd}			1			
Gate Resistance	R_{g}	f = 1 MHz	0.6	2.2	5.1	Ω	
Turn-On Delay Time	t _{d(on)}			4	6		
Rise Time	t _r	$V_{DD} = 30 \text{ V}, R_L = 20 \Omega$		10	15		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1.5 A, V_{GEN} = 10 V, R_G = 1 Ω		10	15	ns	
Fall Time	t _f			7	10.5		
Turn-On Delay Time	t _{d(on)}			15	23		
Rise Time	t _r	V_{DD} = 30 V, R_L = 20 Ω		16	24	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D = 1.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_G = 1 \Omega$		11	17		
Fall Time	t _f			11	17		
Drain-Source Body Diode Characteristic	cs						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.19	۸	
Pulse Diode Forward Current ^a	I _{SM}				7	A	
Body Diode Voltage	V_{SD}	I _S = 1.5 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			15	23	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 45 A 31/31 400 A/ T 67-00		10	15	nC	
Reverse Recovery Fall Time	t _a	$I_F = 1.5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12			
Reverse Recovery Rise Time	t _b			3		ns	

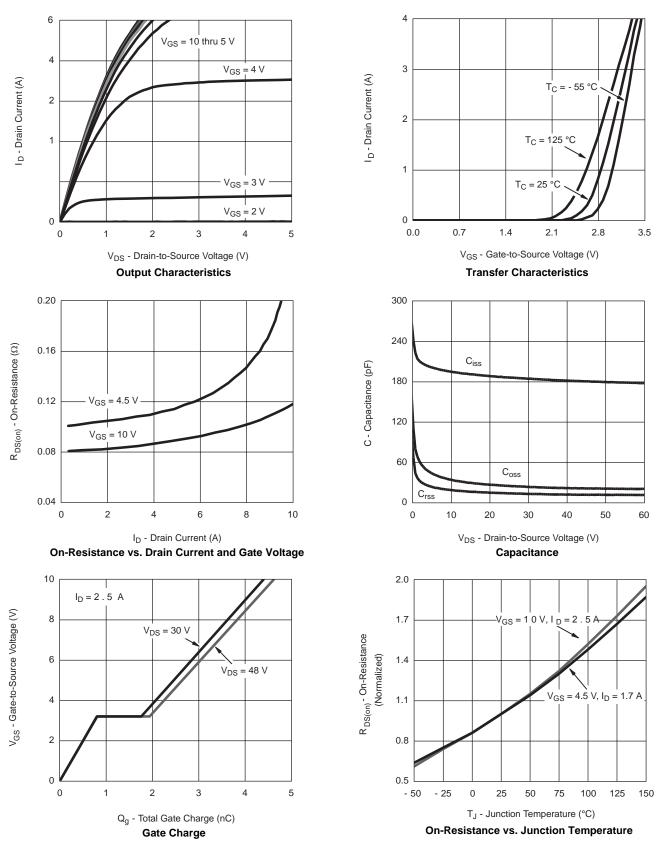
Notes:

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

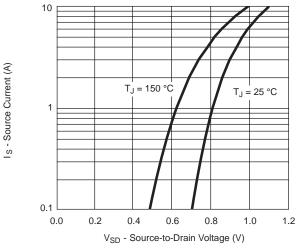


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

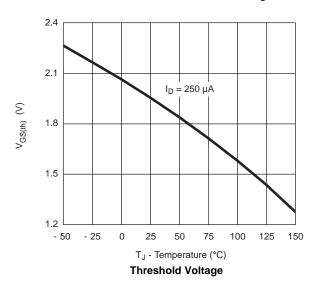


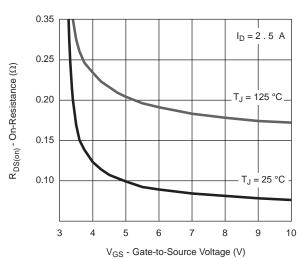


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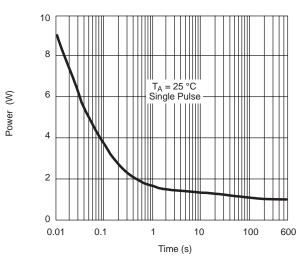


Source-Drain Diode Forward Voltage

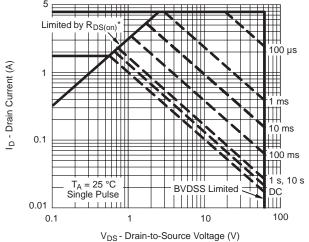




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power

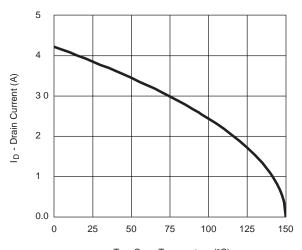


Safe Operating Area

^{*} V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

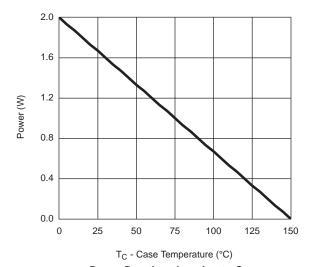


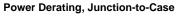
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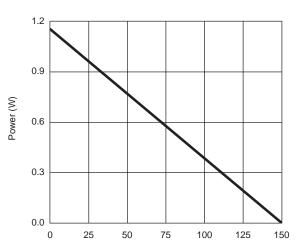


T_C - Case Temperature (°C)

Current Derating*





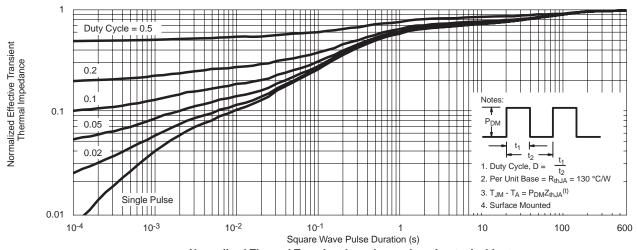


T_A - Ambient Temperature (°C) **Power Derating, Junction-to-Ambient**

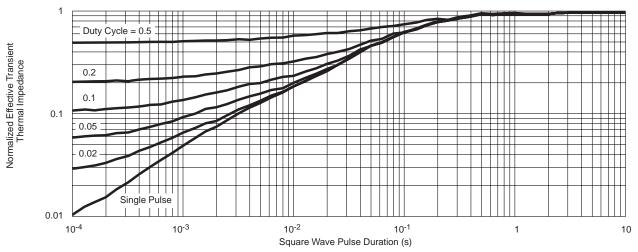
^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



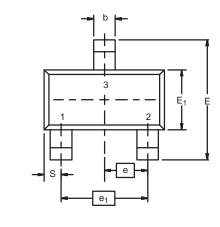
Normalized Thermal Transient Impedance, Junction-to-Ambient

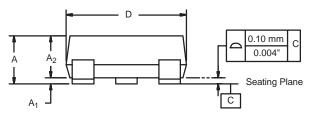


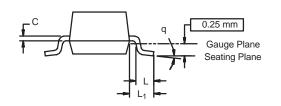
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
Α	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
С	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
е	0.95	0.95 BSC		4 Ref
e ₁	1.90	1.90 BSC		8 Ref
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025	Ref
S	0.50 Ref		0.020) Ref
q	3°	8°	3°	8°

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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